Operating Voltage Range of 4.5 V to 5.5 V

- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 12 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible

SN54HCT3 SN74HCT37		WORN	
CLKEN 1Q 1D 2D 2Q 3Q 3D 4D 4D 4Q GND	1 2 3 4 5 6 7 8 9 10	20 19 18 17 16 15 14 13 12 11	V _{CC} 8Q 8D 7D 7Q 6Q 6D 5D 5Q CLK

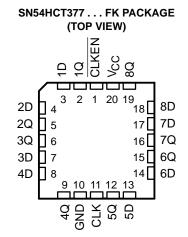
Contain Eight Flip-Flops With Single-Rail Outputs

SN54HCT377, SN74HCT377 OCTAL D-TYPE FLIP-FLOPS

SCLS067D - NOVEMBER 1988 - REVISED MARCH 2003

WITH CLOCK ENABLE

- Clock Enable Latched to Avoid False Clocking
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators



description/ordering information

These devices are positive-edge-triggered D-type flip-flops. The 'HCT377 devices are similar to the 'HCT273 devices, but feature a latched clock-enable (CLKEN) input instead of a common clear.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse if CLKEN is low. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output. These devices are designed to prevent false clocking by transitions at CLKEN.

TA	PACKAG	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HCT377N	SN74HCT377N
–40°C to 85°C		Tube	SN74HCT377DW	HCT377
	SOIC – DW		SN74HCT377DWR	
	CDIP – J	Tube	SNJ54HCT377J	SNJ54HCT377J
–55°C to 125°C	55°C to 125°C CFP – W		SNJ54HCT377W	SNJ54HCT377W
	LCCC – FK	Tube	SNJ54HCT377FK	SNJ54HCT377FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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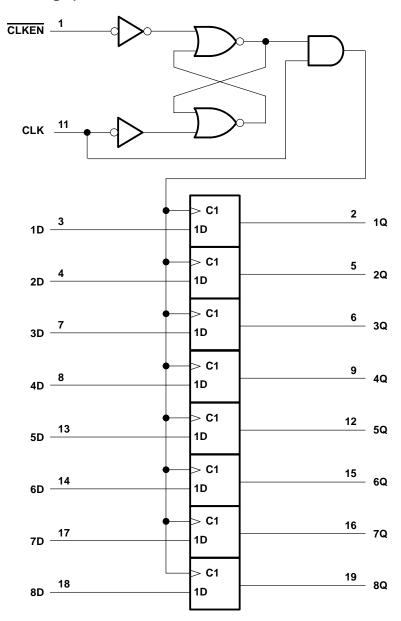


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FUNCTION TABLE

	(each flip-flop)											
I	OUTPUT											
CLKEN	CLK	D	Q									
Н	Х	Х	Q ₀									
L	\uparrow	Н	н									
L	\uparrow	L	L									
х	L	Х	Q ₀									

logic diagram (positive logic)





SN54HCT377, SN74HCT377 OCTAL D-TYPE FLIP-FLOPS WITH CLOCK ENABLE

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	54HCT37	7	SN	74HCT3	77	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	2	'VIE		2			V
VIL	Low-level input voltage	V_{CC} = 4.5 V to 5.5 V		R	0.8			0.8	V
VI	Input voltage		0	E	VCC	0		VCC	V
Vo	Output voltage		0	5	VCC	0		VCC	V
tt	Input transition (rise and fall) times		C	5	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	Vaa	Т	A = 25°C	;	SN54H	СТ377	SN74H	СТ377	UNIT
PARAMETER	TEST CC	INDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vou	$V_{I} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu\text{A}$		4.5 V	4.4	4.499		4.4		4.4		V
VOH	vI = vIH or vIL	I _{OH} = -4 mA	4.5 V	3.98	4.30		3.7	N	3.84		v
Ve	$\lambda = \lambda = 0$	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL	VI = VIH or VIL	I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	v
lj	$V_I = V_{CC} \text{ or } 0$		5.5 V		±0.1	±100	1	±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V			8	Dn.	160		80	μA
∆ICC‡	One input at 0.5 V Other inputs at GN	,	5.5 V		1.4	2.4	10yd	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10*		10	pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.



timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			N	T _A = 2	25°C	SN54H	CT377	SN74H	CT377	
			Vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
f	Clock frequency		4.5 V		25		17		20	MHz
fclock	Clock nequency		5.5 V		30		19		22	
÷	Pulse duration	CLK high or low	4.5 V	20		30		25		ns
t _w	ruise uuralion	CERTIIGHTOFIOW	5.5 V	18		28	ĬEV	23		115
		Data	4.5 V	12		18	IEL	15	15	
	Setup time before CLK1	Dala	5.5 V	10		17	2	14		ns
t _{su}	Setup time before CLK		4.5 V	12		18		15		115
		CLKEN high or low	5.5 V	10		17		14		
		Data	4.5 V	3		\$ 3		3		
+ .	Hold time data after CLK↑	CLKEN inactive or active	5.5 V	3		3		3		20
^t h			4.5 V	5		5		5		ns
			5.5 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	50.01	70			SN	54HCT3	77			
PARAMETER	FROM (INPUT)		(OUTPUT)	Vcc	Т	∖ = 25°C		MIN	МАХ	UNIT
		(6611 61)		MIN	TYP	MAX		IVIAA		
4			4.5 V	25	31	11.	17		MHz	
[†] max			5.5 V	30	37	RE	19			
÷ .	<u>CLK</u>	Anv	4.5 V		15	30		45		
^t pd	CLK	Any	5.5 V		12	ر 28		40	ns	
4		Anv	4.5 V		8	15		22		
tt		Any	5.5 V		6	14		21	ns	

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	50.01	70			SN	74HCT3	77		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	Vcc	T _A = 25°C			MIN	МАХ	UNIT
	((001101)		MIN	TYP	MAX	IVIIIN		
4			4.5 V	25	31		20		MHz
^f max			5.5 V	30	37		22		111112
.	<u>OLK</u>	Anv	4.5 V		15	30		38	
^t pd	CLK	Any	5.5 V		12	28		35	ns
		Apv	4.5 V		8	15		19	
t _t		Any	5.5 V		6	14		17	ns

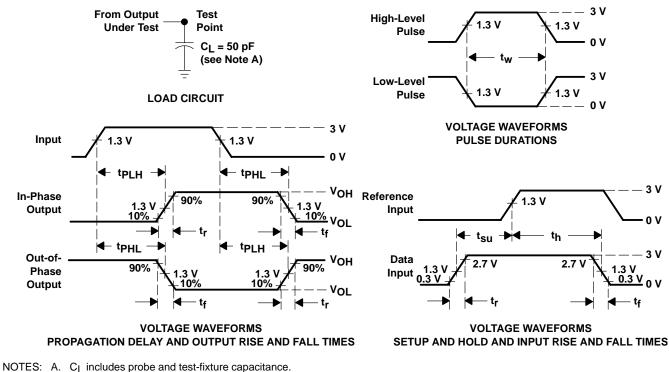
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	No load	30	pF



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PARAMETER MEASUREMENT INFORMATION



- - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. For clock inputs, $f_{\mbox{max}}$ is measured when the input duty cycle is 50%.
 - E. tpl H and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN74HCT377DW	LIFEBUY	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT377	
SN74HCT377DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT377	Samples
SN74HCT377N	ACTIVE	PDIP	Ν	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT377N	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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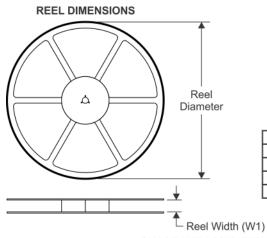
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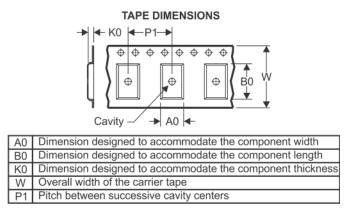
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	•	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT377DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1



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PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HCT377DWR	SOIC	DW	20	2000	367.0	367.0	45.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
SN74HCT377DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74HCT377N	N	PDIP	20	20	506	13.97	11230	4.32

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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